

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	559	347/50.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/30 08:44
L2	338274	((electric\$2 near4 connection) wir\$3 fpc cable lead) with (through between protrude)) same (layer substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/30 08:47
L3	204	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/30 08:47
L4	67	3 and piezoelectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/30 08:47
L5	8	("4695854" "4698644" "4703333" "4768266" "5105209" "5515086" "5684520" "5880763").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/30 08:55
L20	8	("4695854" "4698644" "4703333" "4768266" "5105209" "5515086" "5684520" "5880763").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/30 09:01
S1	2	"20040109046"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:25
S2	4813	347/20,50,54,68-72.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:25
S3	31343	(fpc (flexible adj printed adj circuit) wir\$3) with (protrusion protrud\$3 (draw adj out) (jut adj out))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:27
S4	63	(fpc (flexible adj printed adj circuit) wir\$3) with (protrusion protrud\$3 (draw adj out) (jut adj out)) same ((electric\$4 with connect) with (power supply))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:28
S5	0	S2 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:28
S6	158	(fpc (flexible adj printed adj circuit) wir\$3) same (protrusion protrud\$3 (draw adj out) (jut adj out)) same ((electric\$4 with connect) with (power supply))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:28
S7	336	(fpc (flexible adj printed adj circuit) wir\$3) same (protrusion protrud\$3 (draw adj out) (jut adj out)) same ((electric\$4 with connect) same (power supply))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:40

S8	0	S2 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:28
S9	0	S2 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:28
S10	60992	"347"/\$.ccds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:29
S11	1	S7 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:29
S12	53	S2 and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:29
S13	6	("4940413" "5227812" "5796416" "6186613" "6188414" "6325488").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/06 13:00
S14	2	jp-2000108344-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:30
S15	2	jp-2000094673-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:28
S16	82937	(lnk liquid fluid) same (drip\$3 leak\$3) with (adhesive glu\$3 seal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:36
S17	187	S2 and S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:38
S18	936	(lnk liquid fluid) same (drip\$3 leak\$3) with (adhesive glu\$3 seal\$3) with (electrode (electric\$2 adj connection))".	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:33
S19	936	(lnk liquid fluid) same (drip\$3 leak\$3) with (adhesive glu\$3 seal\$3) with (electrode (electric\$2 adj connection))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:42
S20	4	S2 and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:33

S21	96	S2 and S16 and piezoelectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:36
S22	2024	(Ink liquid fluid) same (drip\$3 leak\$3) same (adhesive glu\$3 seal\$3) with (electrode (electric\$2 adj connection)) same electr\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:45
S23	13	S2 and S22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:42
S24	2024	(Ink liquid fluid) same (drip\$3 leak\$3) same (adhesive glu\$3 seal\$3) with (electrode (electric\$2 adj connection)) with electr\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:45
S25	4941	(Ink liquid fluid) same (drip\$3 leak\$3) same (adhesive glu\$3 seal\$3) with electr\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:45
S26	15	S2 and S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:45
S27	0	("6802596").URPN.	USPAT	OR	ON	2005/04/06 13:55
S28	4810	347/20,50,54,68-72.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:40
S29	2997244	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:41
S30	162278	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable) with (seal\$3 glue bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:42
S31	286	S28 and S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:41
S32	79	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable) with (seal\$3 glue bond\$3) with (print\$2head)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:45
S33	87	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable flexible) with (seal\$3 glue bond\$3) with (print\$3head)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:46

S34	87	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable flexible) with (seal\$3 glue bond\$3 relief) with (print\$3head)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 07:47
S35	88	(protrusion protrud\$3 hole through) with (wire connect\$3 fpc cable flexible) with (seal\$3 glue bond\$3 stress strain) with (print\$3head)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:05
S36	6734	(protrusion protrud\$3 through) with (seal\$3 glu\$3 bond\$3) with (electrical same (wire fpc circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:07
S37	4810	347/20,50,54,68-72.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:11
S38	6734	(protrusion protrud\$3 through) with (seal\$3 glu\$3 bond\$3) with (electrical same (wire fpc circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:11
S39	20	S37 and S38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:18
S40	263	(electric\$2 near5 connection) with (internal external) with piezoelectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/30 08:45
S41	24	S37 and S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:19
S42	5230	347/20,50,54,68-72.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 13:44
S43	5778	347/20,42,50,54,68-73.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 13:44
S44	16971	pot\$3 with (glue adhesive plastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 13:47
S45	34	S43 and S44	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 13:45

S46	1173	(pot\$3 with (glue adhesive plastic)) same electric\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 13:50
S47	64360	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 13:47
S48	8	S46 and S47	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 13:48
S49	4	((pot\$3 with (glue adhesive plastic)) same electric\$3) and (ink with jet)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 14:10
S50	193	(pot\$3 with (glue adhesive plastic)) same (electric\$3 with circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 14:03
S51	0	S43 and S50	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 14:04
S52	193	S44 and S50	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 14:09
S53	1	S47 and S50	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 14:04
S54	16	(US-20020030715-\$ or US-20040032468-\$ or US-20040109046-\$).did. or (US-4412232-\$ or US-4766448-\$ or US-5227812-\$ or US-6188414-\$ or US-6341845-\$ or US-6450617-\$ or US-6543880-\$ or US-6637870-\$ or US-6676247-\$ or US-6799833-\$ or US-6802596-\$ or US-6834937-\$).did. or (GB-2020026-\$).did.	US-PGPUB; USPAT; EPO	OR	ON	2005/12/29 09:30
S55	10	S54 and piezoelectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 09:31
S56	559	347/50.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 09:38
S57	271950	((wir\$3 fpc lead) with (between through)) same (layer substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 09:39

S58	135	S56 and S57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 09:40
S59	72	S58 and (glue adhesive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 09:41
S60	193079	S59 and pzt piezoelectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 09:41
S61	24	S59 and (pzt piezoelectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 09:41